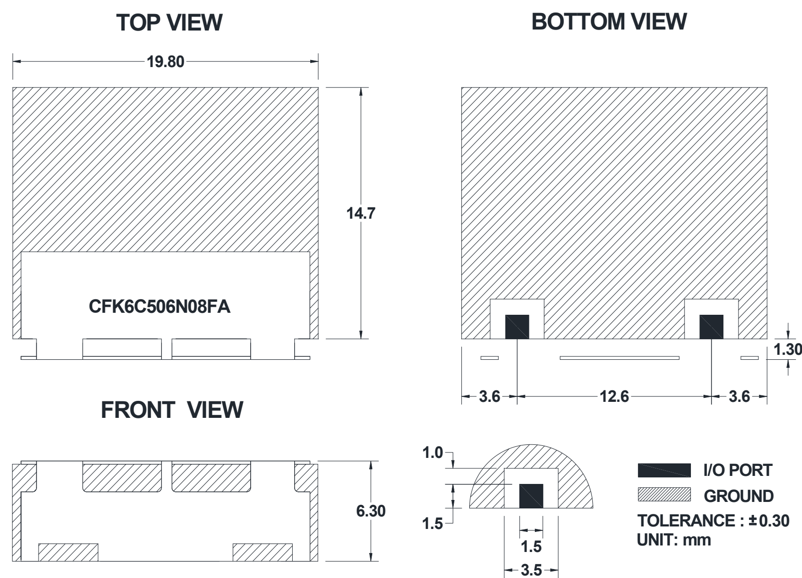
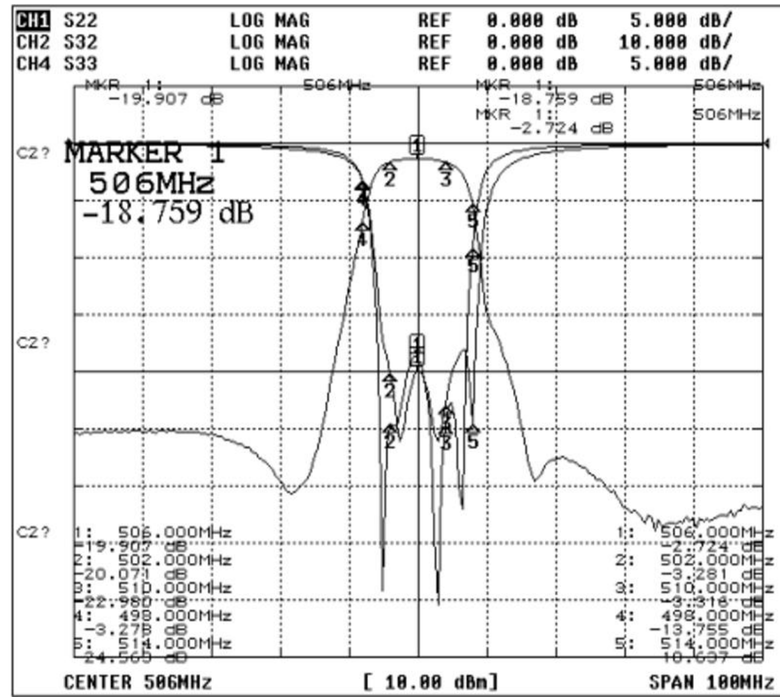
Electrical Specification

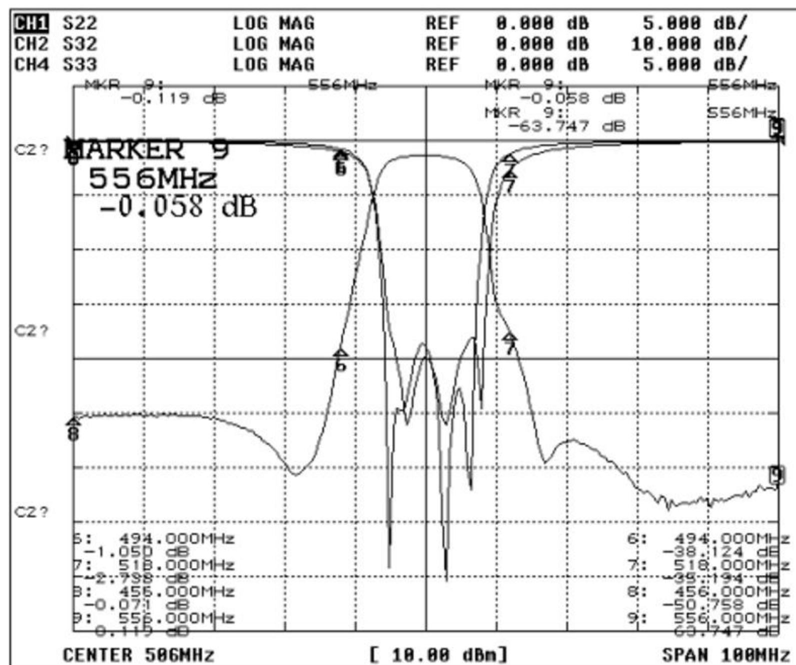
ITEMS	SPEC	UNIT
Center Frequency [fo]	506.0	MHz
Bandwidth [BW]	fo ±4.0 [502.0 ~ 510.0]	MHz
Insertion Loss in BW	3.5	dB max
Ripple in BW	0.8	dB max
Return Loss in BW	15.0	dB min
Attenuation ☑Absolute Value ☐Relative Value	10.0 dB min @ fo ± 8.0 [498.0 & 514.0]	MHz
	20.0 dB min @ fo ± 12.0 [494.0 & 518.0]	MHz
	40.0 dB min @ fo ± 50.0 [456.0 & 556.0]	MHz
	dB min @ fo ± [&]	MHz
Group Delay Variation		ns max
Input Power	2.0	W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40℃ to +85℃	

Mechanical Specification

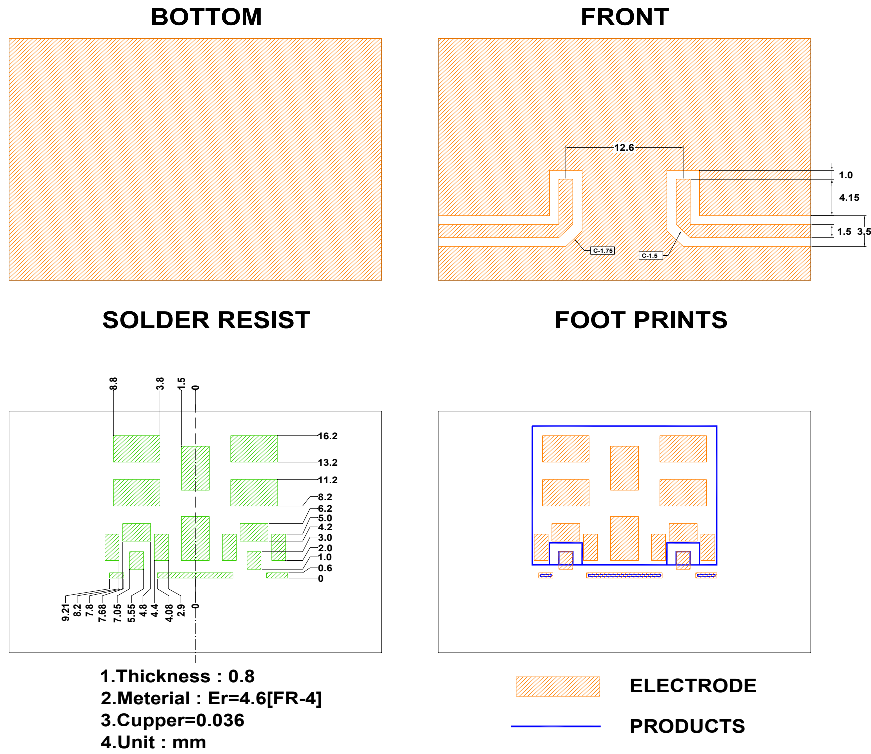


Plot Data

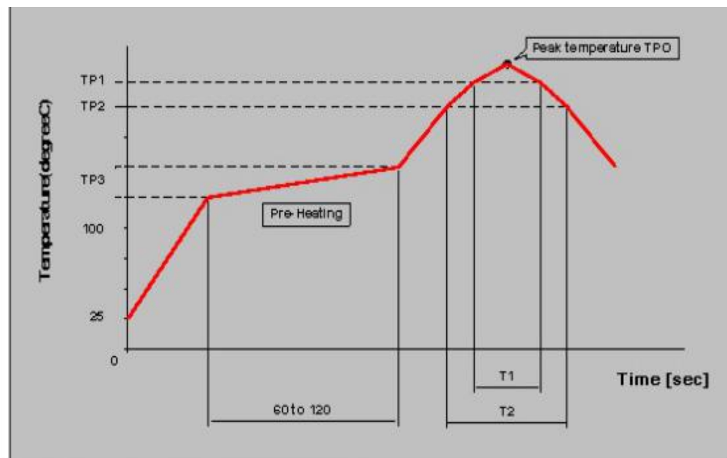




Recommanded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (℃)	TP1 (℃)	T1 (s)	TP2 (℃)	T2 (s)	TP3 (℃)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	__	__	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180